

RFDIP Series – 2012(0805)- RoHS Compliance

MULTILAYER CERAMIC DIPLEXER

Halogens Free Product

2.4 GHz & 5 GHz ISM Band Working Frequency

P/N: RFDIP2012050L7T

*Contents in this sheet are subject to change without prior notice.

Approval sheet



FEATURES

- 1. Miniature footprint: 2.0 X 1.2 X 0.55 mm³.
- 2. Low Profile Thickness
- 3. Low insertion loss
- 4. High attenuation on 2nd harmonic suppressed
- 5. LTCC process

APPLICATIONS

1. Dual-band / Dual-mode.2.4 GHz/ 5 GHz WLAN

CONSTRUCTION



PIN	Connection	PIN	Connection
1	Lower Freq. Port	4	GND
2	GND	5	Common Port
3	Higher Freq. Port	6	GND

DIMENSIONS

Figure	Symbol	Dimension (mm)
L	L	2.00 ± 0.10
	W	1.25 ± 0.20
≥0 ≤	т	0.55 ± 0.15
4	А	0.20 ± 0.15
m	В	0.30 ± 0.15
	С	0.35 ± 0.15
	D	0.65 ± 0.15
	E	0.20 ± 0.10

ELECTRICAL CHARACTERISTICS

RFDIP2012050L7T	Specif	Specification		
Frequency range	2400-2500	4900-5900		
Insertion Loss	0.7 dB max.	1.0 dB max		
VSWR	2.0 max	2.0 max		
Impedance	50	50Ω		
Attenuation (min.)	18 min@ 4.8-6.0GHz 18 min@ 7.2-7.5 GHz	19 min@ 1.8-2.5GHz 25 min@ 10.3-10.7GHz		
Operation Temperature Range	-40°C ~	-40°C ~ +85°C		
Typical Electrical Chart	i			



SOLDER LAND PATTERN



Line width to de designed to match 50 Ω characteristic impedance, depending on PCB material and thickness. Grounding through holes is 0.3 mm



RELIABILITY TEST

Test item	Test condition / Test method	Specification
Solderability JIS C 0050-4.6	*Solder bath temperature : $235 \pm 5^{\circ}$ C	At least 95% of a surface of each terminal
JESD22-B102D	*Immersion time : 2 ± 0.5 sec	electrode must be covered by fresh solder.
	*Solder : Sn3Ag0.5Cu for lead-free	
Leaching (Resistance to dissolution of metallization) IEC 60068-2-58	*Solder bath temperature : 260 ± 5°C *Leaching immersion time : 30 ± 0.5 sec *Solder : SN63A	Loss of metallization on the edges of each electrode shall not exceed 25%.
Resistance to soldering heat	*Preheating temperature : 120~150°C,	No mechanical damage.
JIS C 0050-5.4	1 minute.	Samples shall satisfy electrical specification
	*Solder temperature:270±5°C	after test.
	*Immersion time: 10±1 sec	Loss of metallization on the edges of each
	*Solder : Sn3Ag0.5Cu for lead-free	electrode shall not exceed 25%.
	Measurement to be made after keeping at	
	room temperature for 24±2 hrs	
Drop Test JIS C 0044	*Height : 75 cm *Test Surface : Rigid surface of concrete or steel. *Times : 6 surfaces for each units : 2 times for each side.	No mechanical damage. Samples shall satisfy electrical specification after test.
Adhesive Strength of Termination JIS C 0051- 7.4.3	*Pressurizing force: 5N(≦0603);10N(>0603) *Test time:10±1 sec	No remarkable damage or removal of the termination.
Bending test JIS C 0051- 7.4.1	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and then pressure shall be maintained for 5±1 sec. Measurement to be made after keeping at	No mechanical damage. Samples shall satisfy electrical specification after test.
	room temperature for 24±2 hours	



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Temperature cycle		
JIS C 0025	1. 30±3 minutes at -40°C±3°C,	No mechanical damage.
510 0 0025	2. 10~15 minutes at room temperature,	Samples shall satisfy electrical
	3. 30±3 minutes at +85°C±3°C,	specification after test.
	4. 10~15 minutes at room temperature,	
	Total 100 continuous cycles	
	Measurement to be made after keeping at	
	room temperature for 24±2 hrs	
Vibration	*Frequency : 10Hz~55Hz~10Hz(1min)	No mechanical damage.
JIS C 0040	*Total amplitude : 1.5mm	Samples shall satisfy electrical specification
	*Test times : 6hrs.(Two hrs each in three	after test.
	mutually perpendicular directions)	
High temperature	*Temperature : 85°C±2°C	No mechanical damage.
JIS C 0021	*Test duration : 1000+24/-0 hours	Samples shall satisfy electrical specification
	Measurement to be made after keeping at	after test.
	room temperature for 24±2 hrs	
Humidity	*Humidity : 90% to 95% R.H.	No mechanical damage.
(steady conditions)	*Temperature : 40±2°C	Samples shall satisfy electrical specification
JIS C 0022	*Time : 1000+24/-0 hrs.	after test.
	Measurement to be made after keeping at	
	room temperature for 24±2 hrs	
	st 500hrs measuring the first data then	
	1000hrs data	
Low temperature	*Temperature : -40°C±2°C	No mechanical damage.
JIS C 0020	*Test duration : 1000+24/-0 hours	Samples shall satisfy electrical specification
	Measurement to be made after keeping at	after test.
	room temperature for 24±2 hrs	

SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,



Fig 2. Infrared soldering profile

ORDERING CODE

RF	DIP	201205	0	L	7	Т
Walsin	Product Code	Dimension code	Unit of dimension	Application	Specification	Packing
RF device	DIP : Diplexer	Per 2 digits of	0 : 0.1 mm	L :	Design code	T : Reeled
		Length, Width, Thickness :	1 :1.0 mm	2.4GHz/5GHz		
		e.g. :				
		2012 =				
		Length 20,				
		Width 12,				
		Thickness 05				

Minimum Ordering Quantity: 2000 pcs per reel. PACKAGING



Index	Ao	Во	ΦD	Т	W
Dimension (mm)	1.40 ± 0.10	$\textbf{2.30} \pm \textbf{0.10}$	1.55 ± 0.05	0.84 ± 0.10	8.0 ± 0.10
Index	E	F	Po	P1	P2
Dimension (mm)	1.75 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.05



Reel dimensions



Taping Quantity:2000 pieces per 7" reel

CAUTION OF HANDLING

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

Storage condition

- (1) Products should be used in 6 months from the day of WALSIN outgoing inspection, which can be confirmed.
- (2) Storage environment condition.
 - Products should be storage in the warehouse on the following conditions.
 - Temperature : -10 to +40°C
 - Humidity : 30 to 70% relative humidity
 - Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
 - Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
 - Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
 - Products should be storage under the airtight packaged condition.